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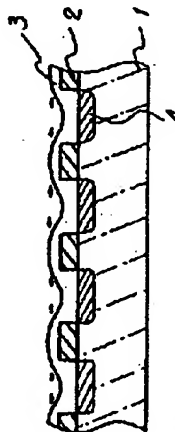
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(54) METHOD FOR DRY-CURING RESIST FILM

(57) Abstract

PURPOSE: To relax the unevenness of the surface of a substrate generated at the time of being formed the resin film on the substrate with difference of the surface level by drying the resist film at a softening temp. of the resist film, followed by curing the dried resist film at a thermosetting temp.

CONSTITUTION: The thermosetting resin 3 is applied on a semiconductor substrate 1 mounted a photodiode 4 and a light shielding film 2 thereon. Next, the obtd. substrate is dried at the softening temp. of the resin 3 for a prescribed period, followed by curing the resin 3 at the thermosetting temp. of the resin 3. Thus, the unevenness of the resin surface 3 due to the film 2 is relaxed, and the smoothness of the resin surface is improved.



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